

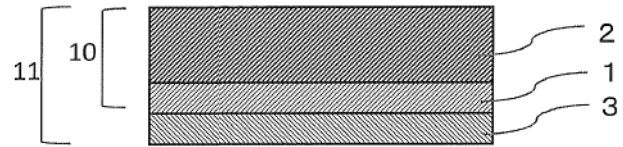
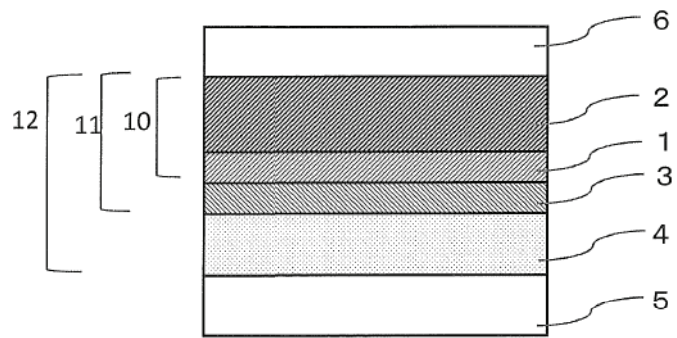
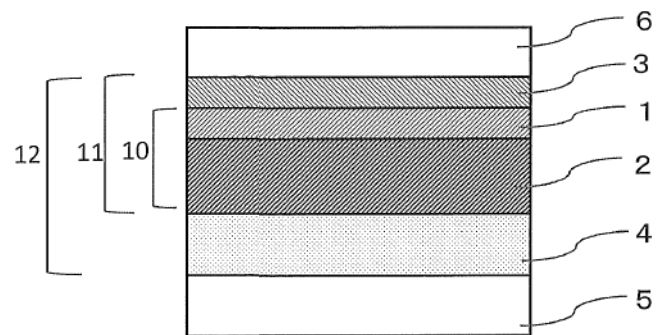
FIG. 1**FIG. 2A****FIG. 2B**

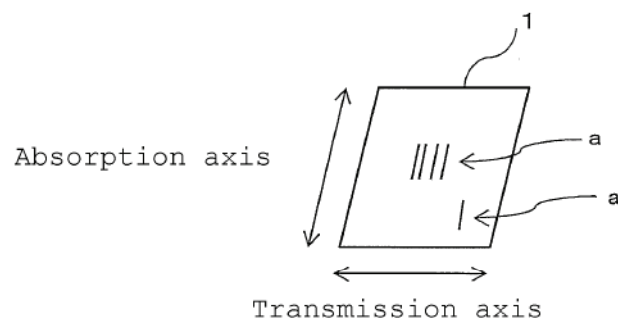
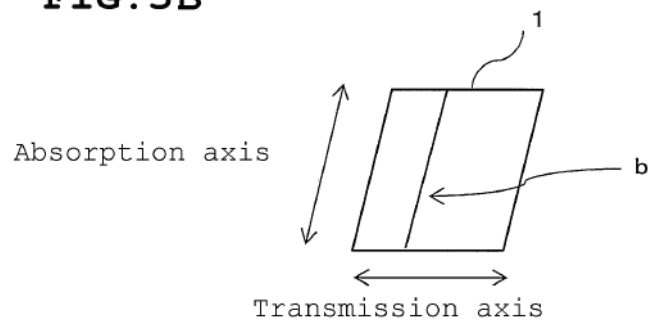
FIG. 3A**FIG. 3B**

FIG. 4A

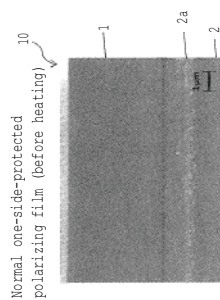
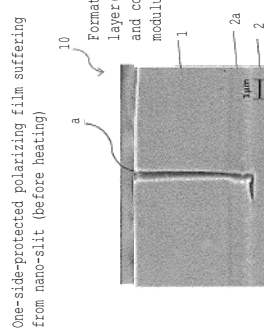
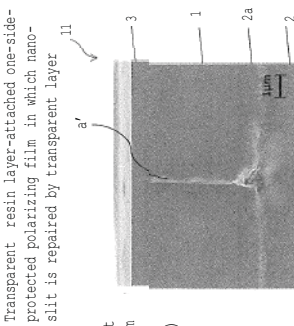


FIG. 4B



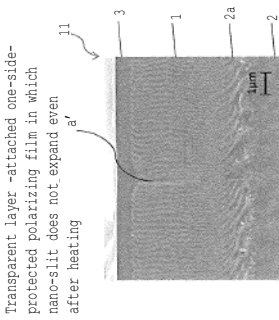
Formation of transparent layer (with thickness 1μm and compressive elastic modulus 0.1 GPa or more)

FIG. 4D



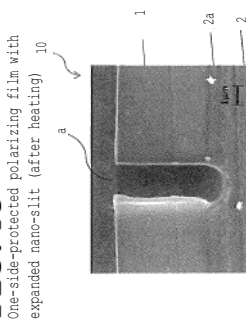
Heating

FIG. 4E



Heating without transparent resin layer

FIG. 4C



Heating after formation of transparent layer (with thickness 1μm and compressive elastic modulus less than 0.1 GPa)

FIG. 4F

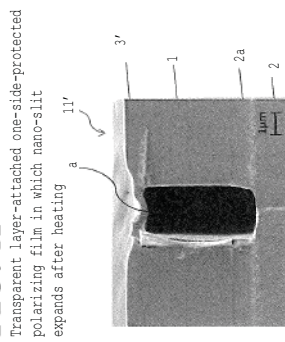


FIG. 5A

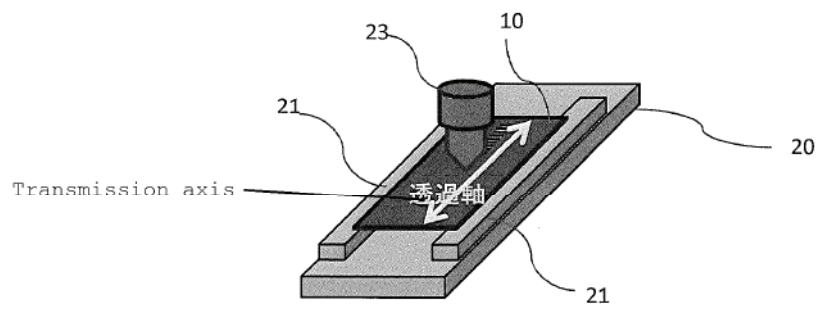


FIG. 5B

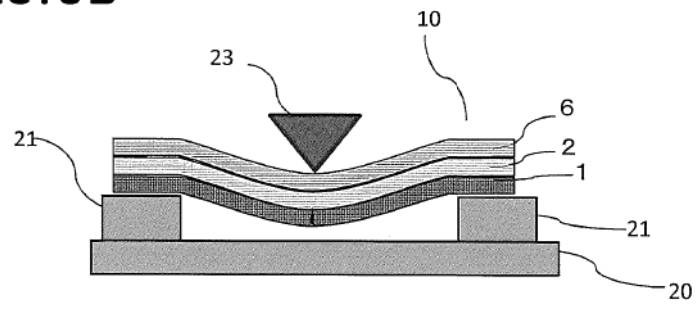


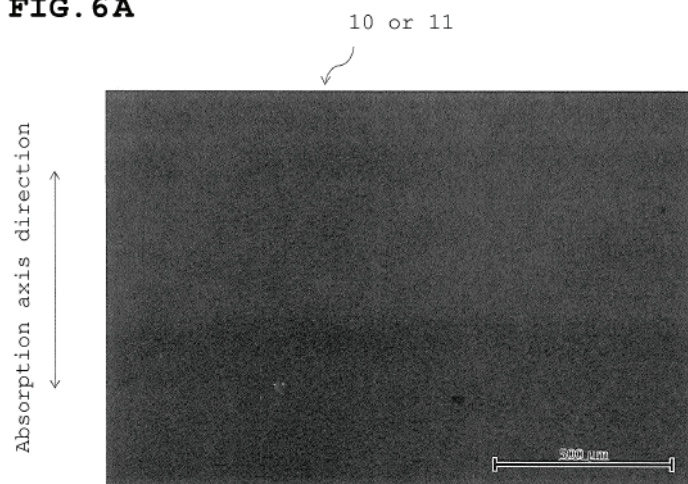
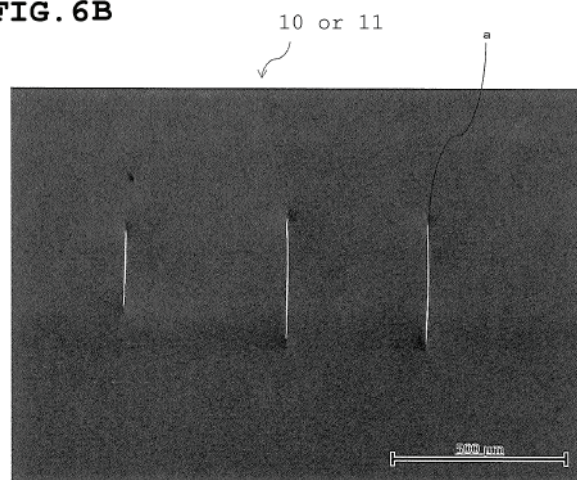
FIG. 6A**FIG. 6B**

FIG. 7

